**Report**

**Date:** August 08, 2023

**Time:** 12:30 PM (IST)

**Location:** Committee Room, Department of Electronics Engineering, IIT (BHU), Varanasi

**Organized by:** IEEE Nanotechnology Council and IEEE Electron Devices Society Student Branch Chapter, IIT (BHU), Varanasi

The Experience Sharing/Discussion Session on "IEEE 30th International Symposium on the Physical and Failure Analysis (IPFA) Of Integrated Circuits" brought together researchers, engineers, and industry professionals. This session aimed to share the valuable experience gained by Dr. Shivam Verma during his visit to Penang Malaysia to attend and present the paper at the IEEE 30th International Symposium on the Physical and Failure Analysis (IPFA) Of Integrated Circuits conference, which was held from July 24 to 27, 2023. The session commenced with a brief introduction of Dr. Verma's visit, highlighting the significance of the paper he presented and its relevance to the field of integrated circuits. Dr. Verma has provided an overview of the IEEE 30th IPFA conference, summarizing its themes, objectives, and the diverse range of research topics discussed during the conference. He also shared his personal experiences during the conference, including interactions with researchers, collaborators, and experts in the field. He discussed the importance of networking and collaborative opportunities. Finally, Dr. Verma concluded the session by highlighting potential future research directions, applications, and areas for further exploration based on the insights gained at the conference.

**The report includes several pictures capturing the key moments of the talk.**

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